

## -150V P-Channel Enhancement Mode MOSFET

### Description

The AP2P15MI uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 10V. This device is suitable for use as a Battery protection or in other Switching application.

### General Features

$V_{DS} = -150V$   $I_D = -2.7A$

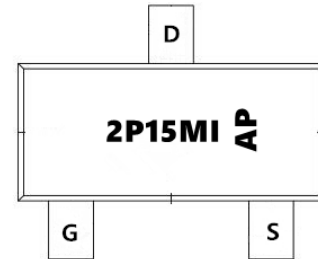
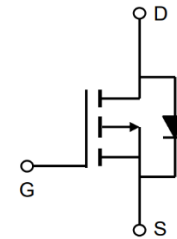
$R_{DS(ON)} < 780m\Omega$  @  $V_{GS}=10V$  (Type: 620m $\Omega$ )

### Application

Brushless motor

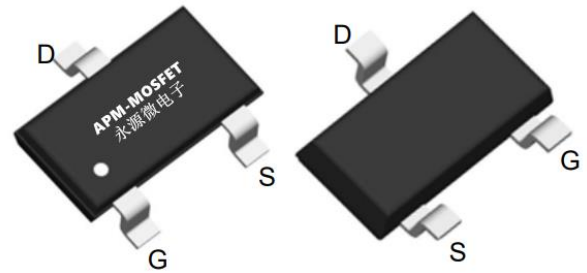
Load switch

Uninterruptible power supply



Top View

Bottom View



### Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
AP2P15MI	SOT-23-3L	AP2P15MI XXX YYYY	3000

### Absolute Maximum Ratings ( $T_C=25^\circ C$ unless otherwise noted)

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	-150	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D@T_A=25^\circ C$	Continuous Drain Current, $-V_{GS}$ @ $-10V^1$	-2.7	A
$I_D@T_A=70^\circ C$	Continuous Drain Current, $-V_{GS}$ @ $-10V^1$	-1.8	A
IDM	Pulsed Drain Current <sup>2</sup>	-8.5	A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	56.5	mJ
IAS	Avalanche Current	5	A
$P_D@T_A=25^\circ C$	Total Power Dissipation <sup>4</sup>	2	W
TSTG	Storage Temperature Range	-55 to 150	$^\circ C$
$T_J$	Operating Junction Temperature Range	-55 to 150	$^\circ C$
$R_{\theta JA}$	Thermal Resistance Junction-Ambient <sup>1</sup>	125	$^\circ C/W$
$R_{\theta JC}$	Thermal Resistance Junction-Case <sup>1</sup>	40	$^\circ C/W$

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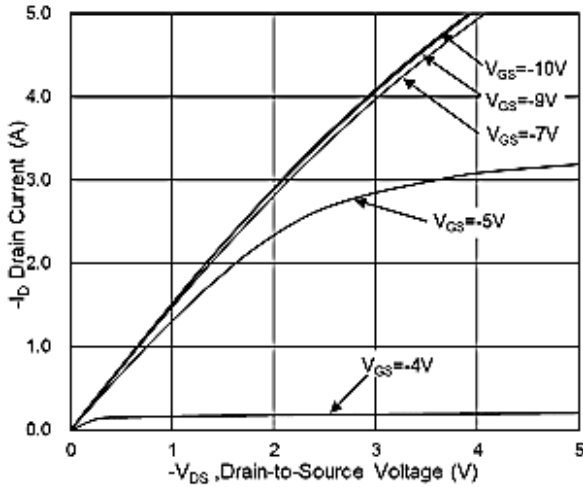
### P-Channel Electrical Characteristics (T<sub>J</sub> =25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BVDSS	Drain-Source Breakdown Voltage	VGS=0V , ID=-250uA	-150	-168	---	V
RDS(ON)	Static Drain-Source On-Resistance	VGS=-10V , ID=-1A	---	620	780	mΩ
RDS(ON)	Static Drain-Source On-Resistance	VGS=-6V , ID=-0.5A	---	700	980	
VGS(th)	Gate Threshold Voltage	VGS=VDS , ID =-250uA	-2.0	-3.0	-4.0	V
IDSS	Drain-Source Leakage Current	VDS=120V ,VGS=0V ,TJ=25°C	---	---	1	uA
IDSS	Drain-Source Leakage Current	VDS=120V ,VGS=0V ,TJ=85°C	---	---	30	uA
IGSS	Gate-Source Leakage Current	VGS=±20V , VDS=0V	---	---	±100	nA
Rg	Gate Resistance	VDS=0V , VGS=0V , f=1MHz	---	12	---	Ω
Qg	Total Gate Charge	VDS=-75V , VGS=-10V , ID=-1A	---	10.8	---	nC
Qgs	Gate-Source Charge		---	3.1	---	nC
Qgd	Gate-Drain Charge		---	2.2	---	nC
Td(on)	Turn-On Delay Time	VDD=-30V , VGS=-10V , RG=6Ω, ID=-1A	---	21	---	ns
Tr	Rise Time		---	16	---	ns
Td(off)	Turn-Off Delay Time		---	40	---	ns
Tf	Fall Time		---	18	---	ns
Ciss	Input Capacitance	VDS=-75V , VGS=0V , f=1MHz	---	706	---	pF
Coss	Output Capacitance		---	23	---	pF
Crss	Reverse Transfer Capacitance		---	13	---	pF

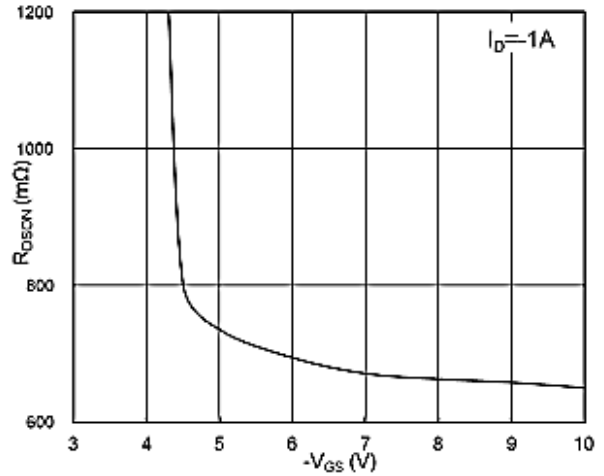
Note :

- 1、 The data tested by surface mounted on a 1 inch 2 FR-4 board with 2OZ copper.
- 2、 The data tested by pulsed , pulse width  $\leq$  300us , duty cycle  $\leq$  2%
- 3、 The power dissipation is limited by 150°C junction temperature
- 4、 The data is theoretically the same as I<sub>D</sub> and I<sub>DM</sub> , in real applications , should be limited by total power dissipation.

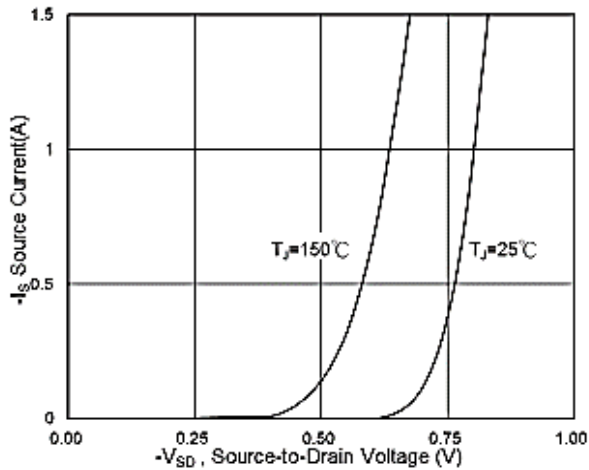
**Typical Characteristics**



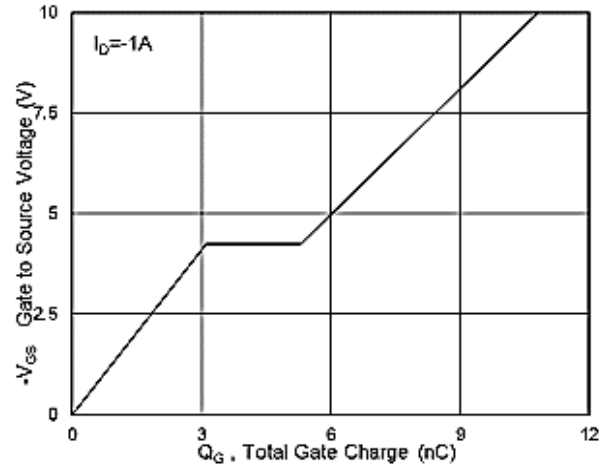
**Fig.1 Typical Output Characteristics**



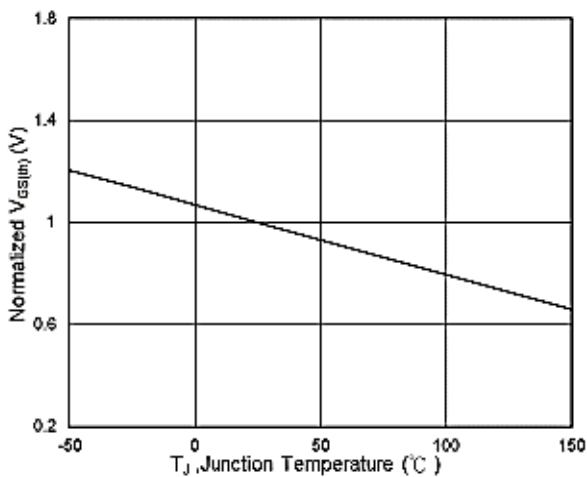
**Fig.2 On-Resistance vs G-S Voltage**



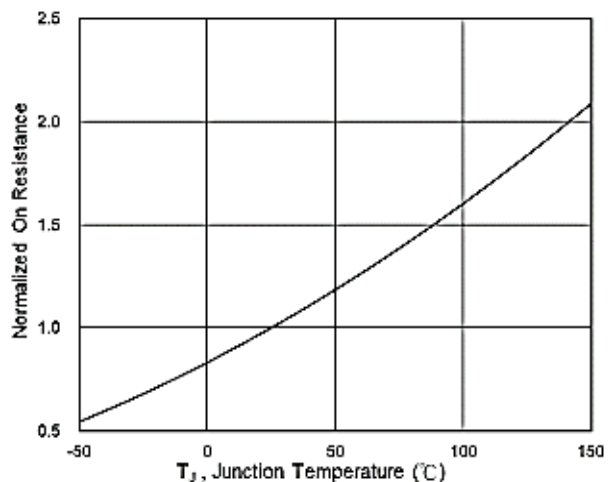
**Fig.3 Source Drain Forward Characteristics**



**Fig.4 Gate-Charge Characteristics**

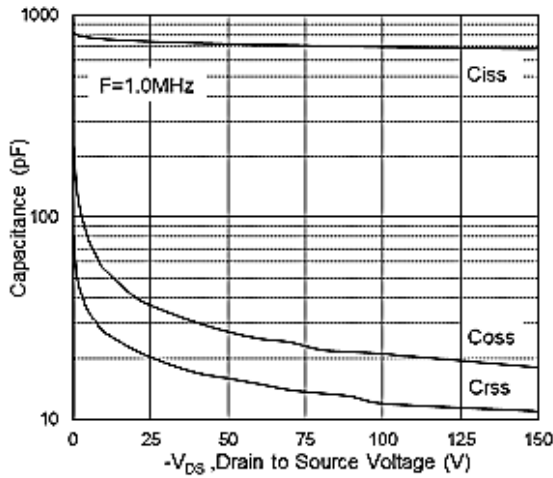


**Fig.5 Normalized  $V_{GS(th)}$  vs  $T_J$**

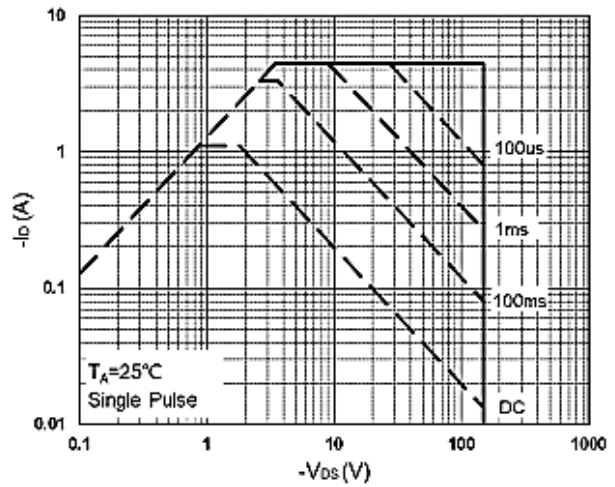


**Fig.6 Normalized  $R_{DS(on)}$  vs  $T_J$**

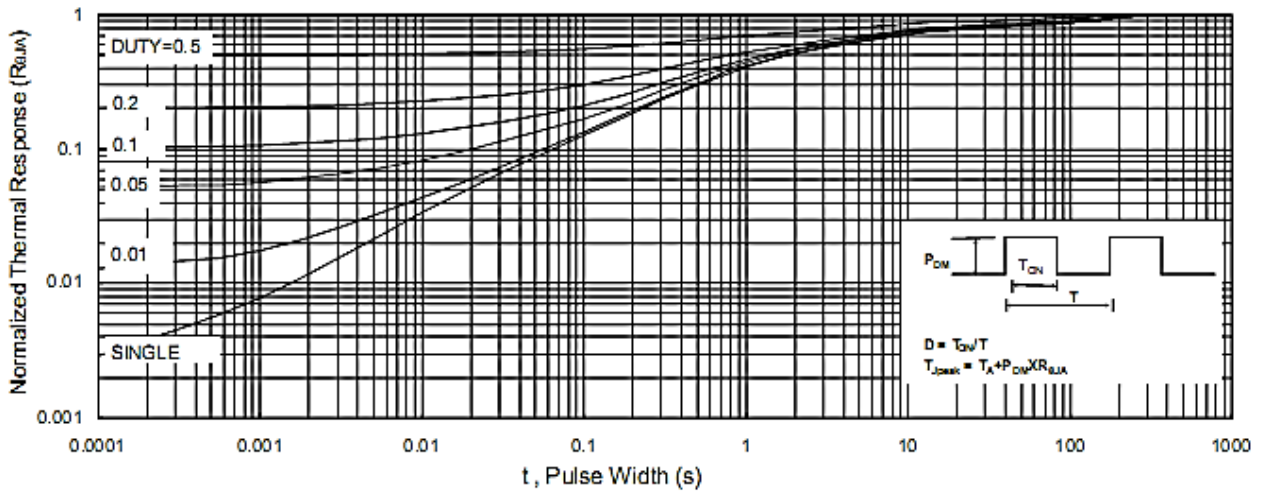
**-150V P-Channel Enhancement Mode MOSFET**



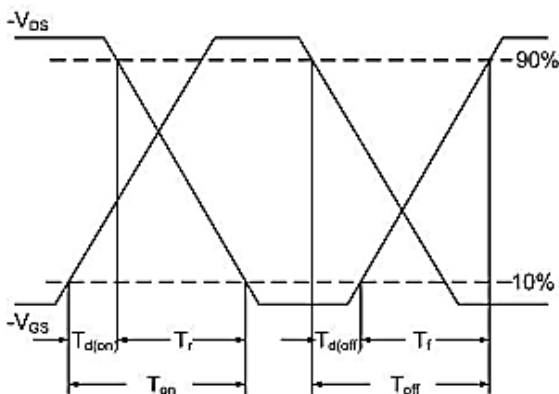
**Fig.7 Capacitance**



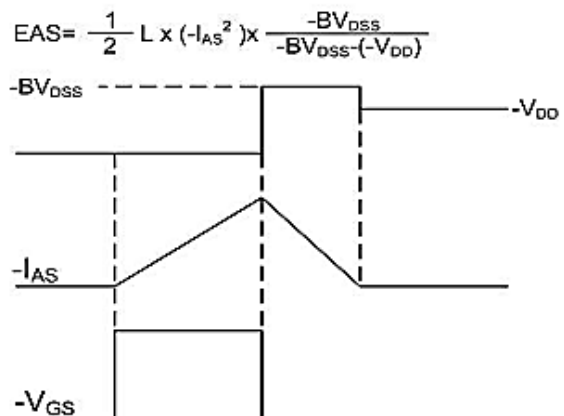
**Fig.8 Safe Operating Area**



**Fig.9 Normalized Maximum Transient Thermal Impedance**



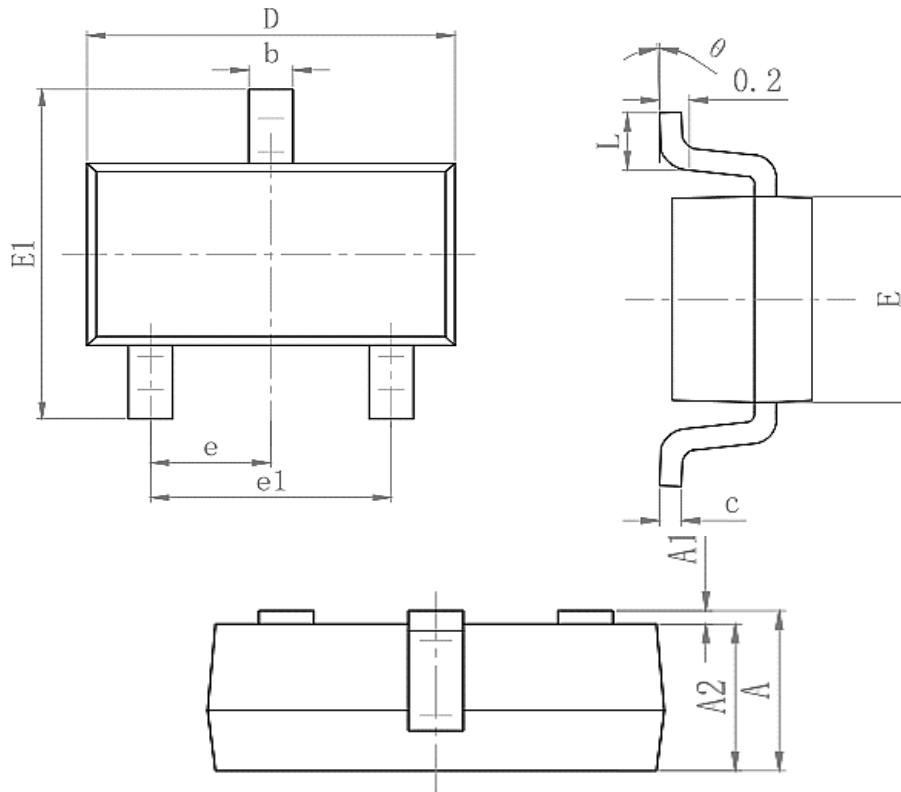
**Fig.10 Switching Time Waveform**



**Fig.11 Unclamped Inductive Waveform**

$$EAS = \frac{1}{2} L \times (-I_{AS}^2) \times \frac{-BV_{DSS}}{-BV_{DSS} - (-V_{DD})}$$

### Package Mechanical Data-SOT23-3-XC-Single



Symbol	Dimensions In Millimeters	
	Min.	Max.
A	1.050	1.250
A1	0.000	0.100
A2	1.050	1.150
b	0.25	0.45
c	0.100	0.200
D	2.820	3.020
E	1.5	1.7
E1	2.650	2.950
e	0.950(BSC)	
e1	1.800	2.000
L	0.300	0.500
$\theta$	0°	8°

**-150V P-Channel Enhancement Mode MOSFET****Attention**

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Edition	Date	Change
Rve1.0	2021/4/13	Initial release

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